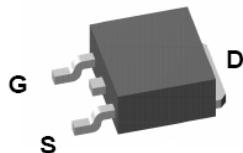


## P2504EDG

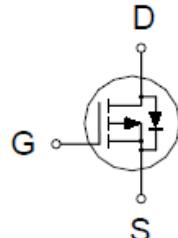
### P-Channel Enhancement Mode MOSFET

#### PRODUCT SUMMARY

$V_{(BR)DSS}$	$R_{DS(ON)}$	$I_D$
-40V	25.8mΩ @ $V_{GS} = -10V$	-18A



TO-252



100% UIS tested  
100% Rg tested

#### ABSOLUTE MAXIMUM RATINGS ( $T_A = 25^\circ C$ Unless Otherwise Noted)

PARAMETERS/TEST CONDITIONS		SYMBOL	LIMITS	UNITS
Drain-Source Voltage		$V_{DS}$	-40	V
Gate-Source Voltage		$V_{GS}$	$\pm 20$	
Continuous Drain Current	$T_C = 25^\circ C$	$I_D$	-18	A
	$T_C = 70^\circ C$		-13.5	
Pulsed Drain Current <sup>1</sup>		$I_{DM}$	-40	
Power Dissipation	$T_C = 25^\circ C$	$P_D$	42	W
	$T_C = 70^\circ C$		27	
Operating Junction & Storage Temperature Range		$T_J, T_{STG}$	-55 to 150	°C

#### THERMAL RESISTANCE RATINGS

THERMAL RESISTANCE		SYMBOL	TYPICAL	MAXIMUM	UNITS
Junction-to-Case		$R_{\theta JC}$		3	°C / W
Junction-to-Ambient		$R_{\theta JA}$		75	

<sup>1</sup>Pulse width limited by maximum junction temperature.

## P2504EDG

### P-Channel Enhancement Mode MOSFET

#### ELECTRICAL CHARACTERISTICS ( $T_J = 25^\circ\text{C}$ , Unless Otherwise Noted)

PARAMETER	SYMBOL	TEST CONDITIONS	LIMITS			UNITS
			MIN	TYP	MAX	
<b>STATIC</b>						
Drain-Source Breakdown Voltage	$V_{(\text{BR})\text{DSS}}$	$V_{\text{GS}} = 0\text{V}, I_D = -250\mu\text{A}$	-40			V
Gate Threshold Voltage	$V_{\text{GS}(\text{th})}$	$V_{\text{DS}} = V_{\text{GS}}, I_D = -250\mu\text{A}$	-1.5	-2.2	-3.0	
Gate-Body Leakage	$I_{\text{GSS}}$	$V_{\text{DS}} = 0\text{V}, V_{\text{GS}} = \pm 20\text{V}$			$\pm 250$	nA
Zero Gate Voltage Drain Current	$I_{\text{DSS}}$	$V_{\text{DS}} = -32\text{V}, V_{\text{GS}} = 0\text{V}$			1	$\mu\text{A}$
		$V_{\text{DS}} = -30\text{V}, V_{\text{GS}} = 0\text{V}, T_J = 125^\circ\text{C}$			10	
On-State Drain Current <sup>1</sup>	$I_{\text{D}(\text{ON})}$	$V_{\text{DS}} = -5\text{V}, V_{\text{GS}} = -10\text{V}$	-40			A
Drain-Source On-State Resistance <sup>1</sup>	$R_{\text{DS}(\text{ON})}$	$V_{\text{GS}} = -7\text{V}, I_D = -10\text{A}$		30	40	$\text{m}\Omega$
		$V_{\text{GS}} = -10\text{V}, I_D = -18\text{A}$		22	25.8	
Forward Transconductance <sup>1</sup>	$g_{\text{fs}}$	$V_{\text{DS}} = -5\text{V}, I_D = -18\text{A}$		20		S
<b>DYNAMIC</b>						
Input Capacitance	$C_{\text{iss}}$	$V_{\text{GS}} = 0\text{V}, V_{\text{DS}} = -15\text{V}, f = 1\text{MHz}$		1570		pF
Output Capacitance	$C_{\text{oss}}$			320		
Reverse Transfer Capacitance	$C_{\text{rss}}$			210		
Total Gate Charge <sup>2</sup>	$Q_g$	$V_{\text{DS}} = 0.5V_{(\text{BR})\text{DSS}}, V_{\text{GS}} = -10\text{V}, I_D = -18\text{A}$		29		nC
Gate-Source Charge <sup>2</sup>	$Q_{\text{gs}}$			6		
Gate-Drain Charge <sup>2</sup>	$Q_{\text{gd}}$			7		
Turn-On Delay Time <sup>2</sup>	$t_{\text{d}(\text{on})}$	$V_{\text{DS}} = -20\text{V}, R_L = 1\Omega$ $I_D \approx -1\text{A}, V_{\text{GS}} = -10\text{V}, R_{\text{GS}} = 6\Omega$		12		nS
Rise Time <sup>2</sup>	$t_r$			29		
Turn-Off Delay Time <sup>2</sup>	$t_{\text{d}(\text{off})}$			42		
Fall Time <sup>2</sup>	$t_f$			33		
<b>SOURCE-DRAIN DIODE RATINGS AND CHARACTERISTICS (<math>T_J = 25^\circ\text{C}</math>)</b>						
Continuous Current	$I_S$				-18	A
Forward Voltage <sup>1</sup>	$V_{\text{SD}}$	$I_F = -18\text{A}, V_{\text{GS}} = 0\text{V}$			-1.3	V
Reverse Recovery Time	$t_{\text{rr}}$	$I_F = -18\text{A}, dI_F/dt = 100\text{A} / \mu\text{s}$		29		nS
Reverse Recovery Charge	$Q_{\text{rr}}$			21		nC

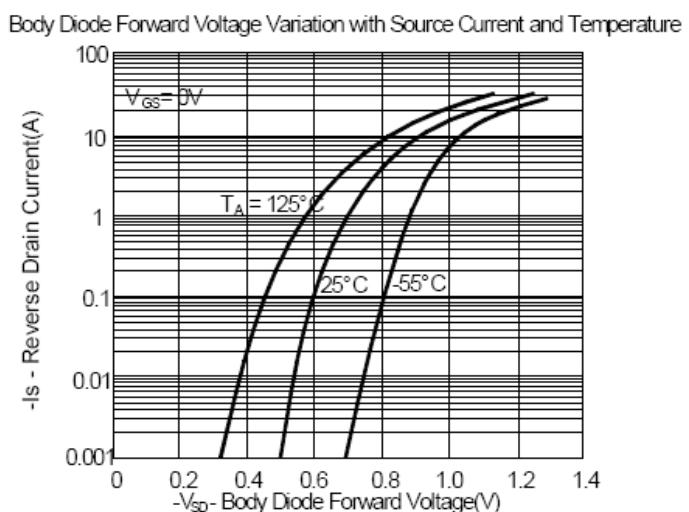
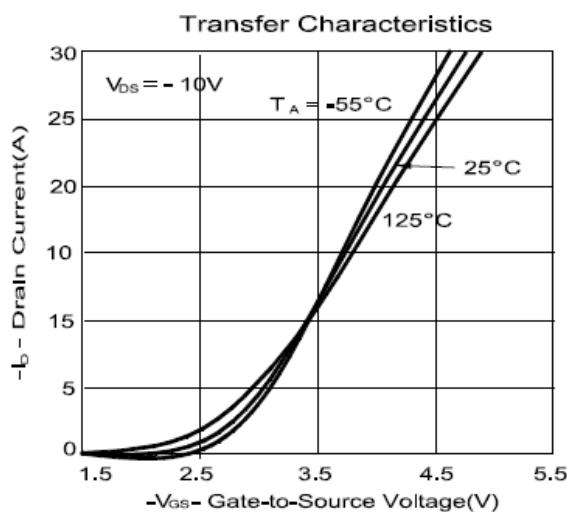
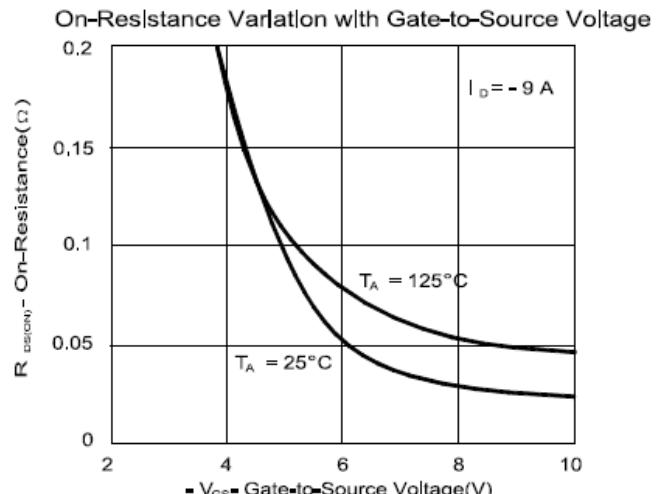
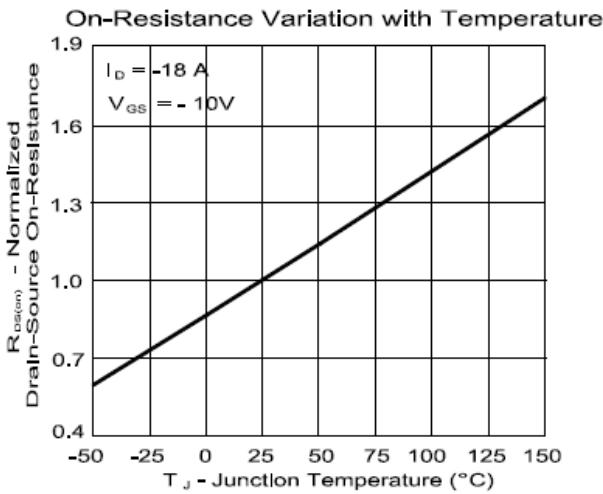
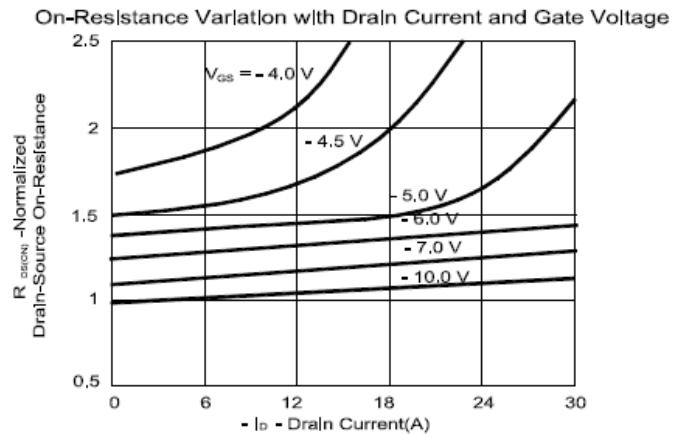
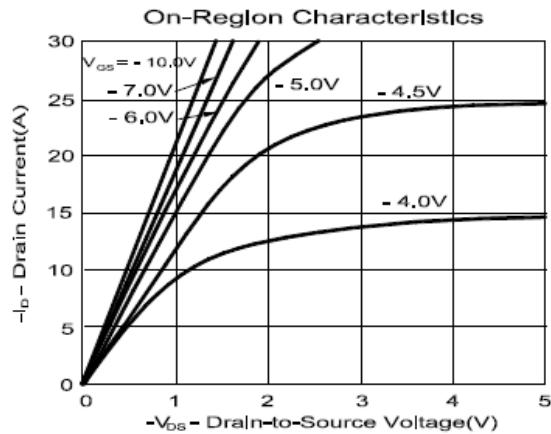
<sup>1</sup>Pulse test : Pulse Width  $\leq 300\ \mu\text{sec}$ , Duty Cycle  $\leq 2\%$ .

<sup>2</sup>Independent of operating temperature.

## P2504EDG

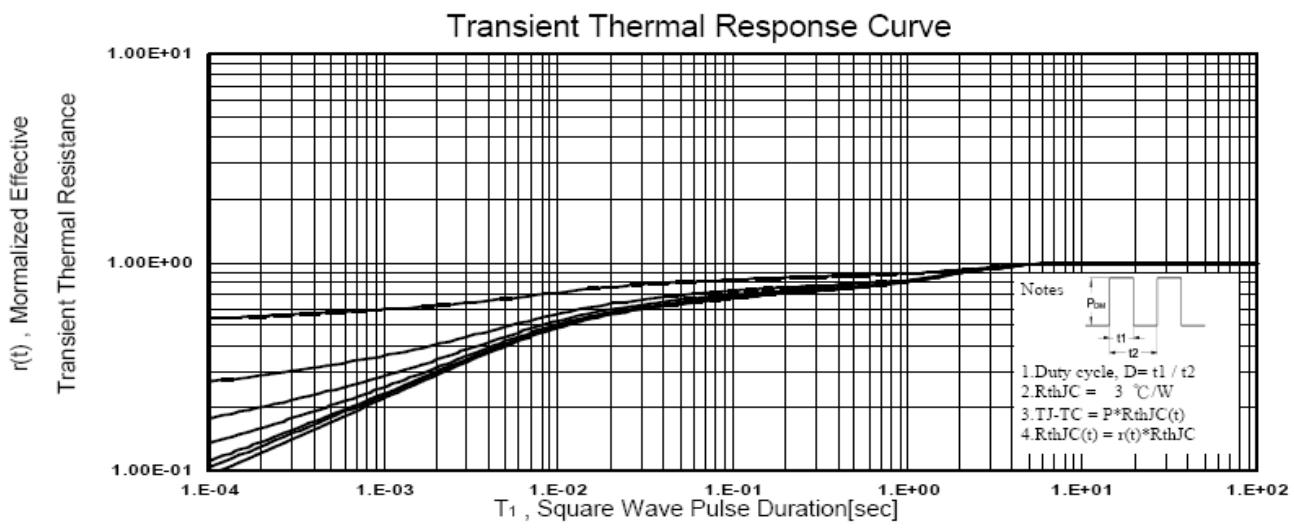
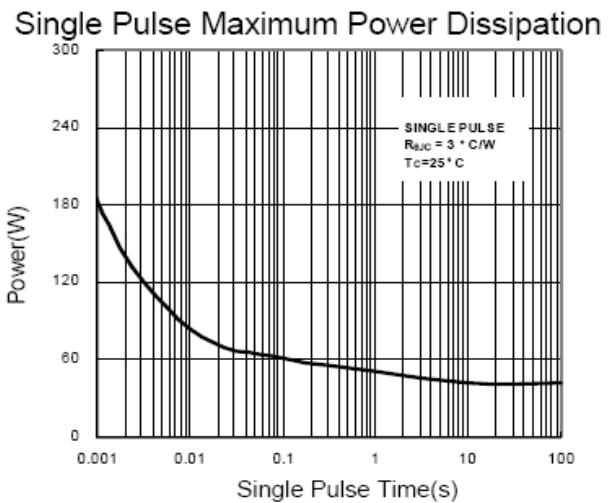
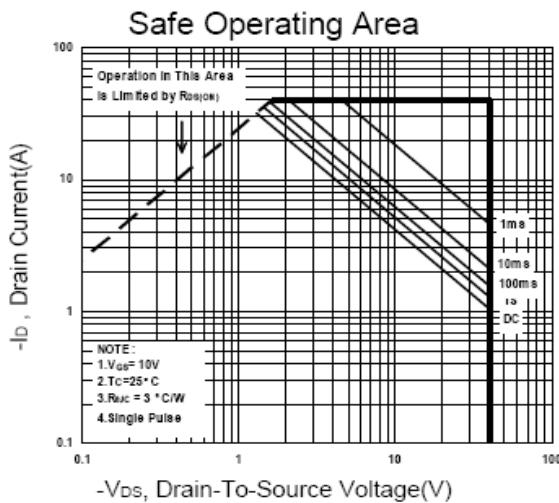
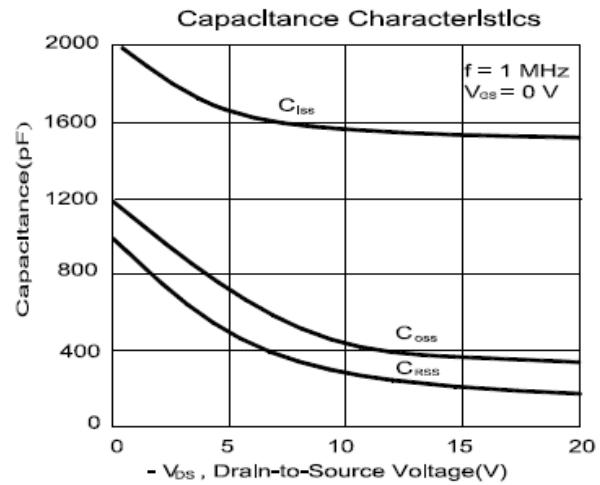
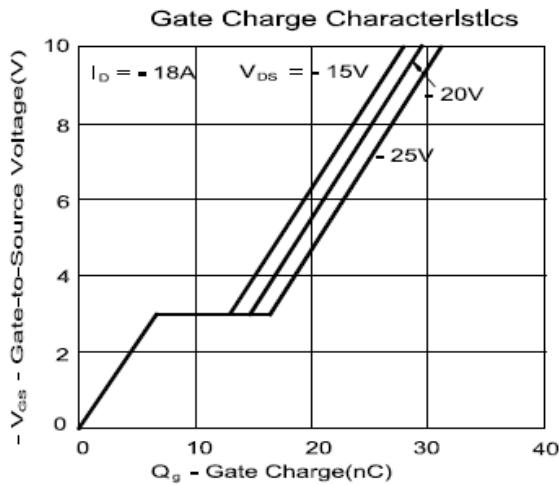
### P-Channel Enhancement Mode MOSFET

#### TYPICAL PERFORMANCE CHARACTERISTICS



## P2504EDG

### P-Channel Enhancement Mode MOSFET



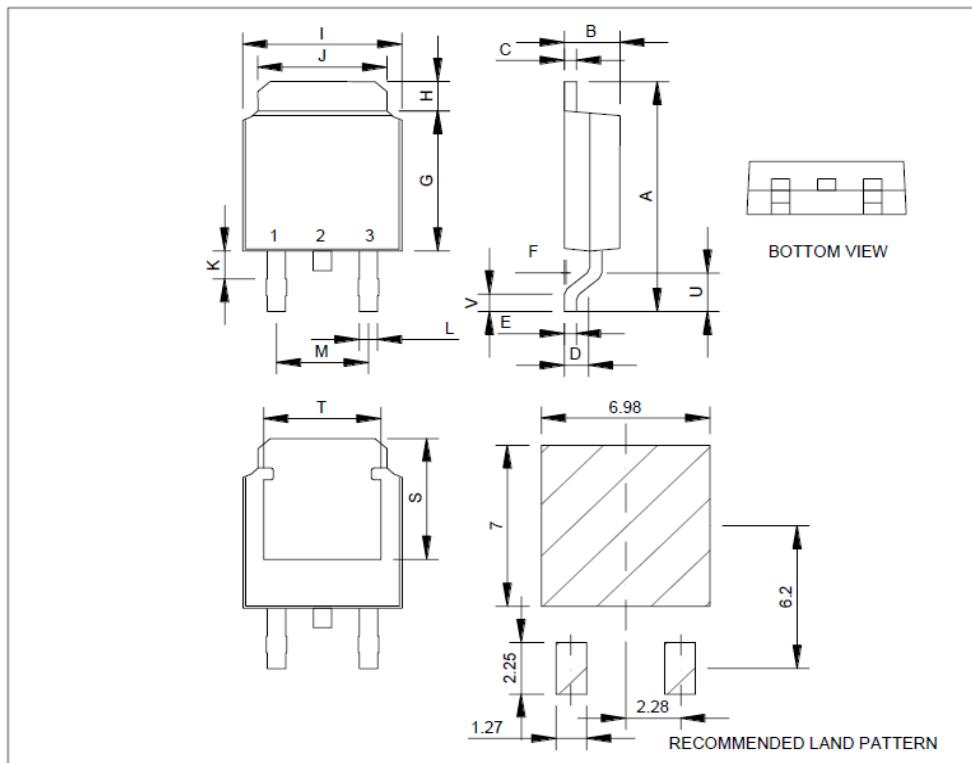
## P2504EDG

### P-Channel Enhancement Mode MOSFET

#### Package Dimension

#### TO-252 (DPAK) MECHANICAL DATA

Dimension	mm			Dimension	mm		
	Min.	Typ.	Max.		Min.	Typ.	Max.
A	8.9	10	10.41	J	4.8		5.64
B	2.1	2.2	2.4	K	0.15		1.1
C	0.4	0.5	0.61	L	0.4	0.76	0.89
D	0.82	1.2	1.5	M	4.2	4.58	5
E	0.4	0.5	0.61	S	4.9	5.1	5.3
F	0		0.2	T	4.6	4.75	5.44
G	5.3	6.1	6.3	U	1.4		1.78
H	0.9		1.7	V	0.55	1.25	1.7
I	6.3	6.5	6.8				

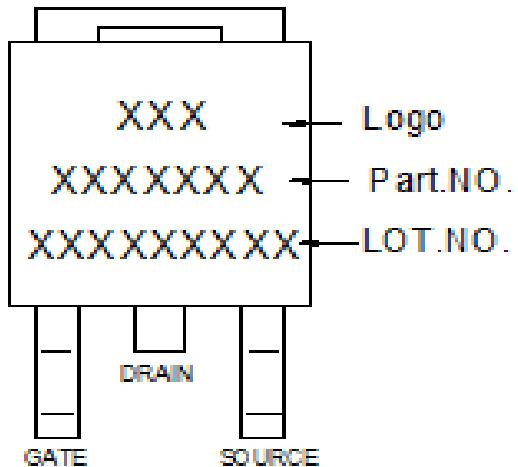


\*因为各家封装模具不同而外观略有差异，不影响电性及Layout。

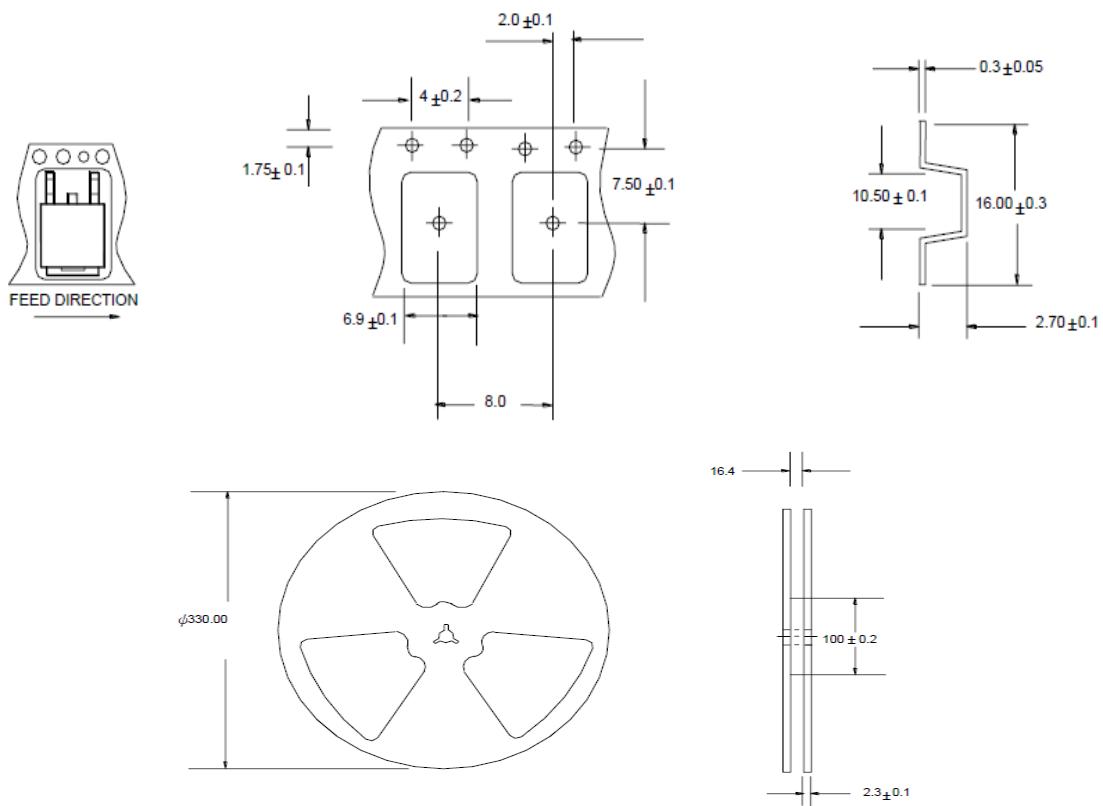
## P2504EDG

### P-Channel Enhancement Mode MOSFET

#### A. Marking Information



#### B. Tape&Reel Information: 2500pcs/Reel



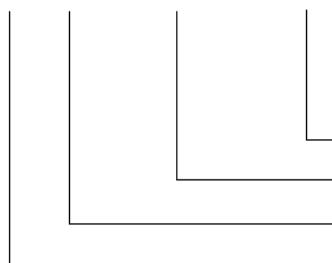
## P2504EDG

### P-Channel Enhancement Mode MOSFET

#### C. Lot.No. & Date Code rule

##### 1.LOT.NO.

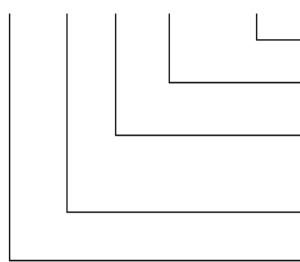
M N 15M21 03



- #8~9 Sub-lot No
- Order series no.
- Foundry site
- Assembly site

##### 2.Date Code

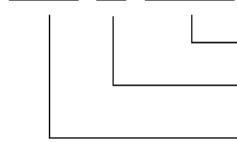
D Y M X XXX



- Order series no. & Sub-lot No
- Week
- M : Month (A:Jan , B:Feb , C:Mar ,D :Apr ,E:May ,F:Jun,G:Jul,H:Aug,I:Sep,J:Oct,K:Nov,L:Dec.)
- Y : Year (N : 2011, O : 2012 ...)
- Assembly site

##### 3.Date Code (for Small package)

XX Y WW



- Week
- Y : Year (9: 2009,A : 2010, B : 2011 ...)
- Device Name

## P2504EDG

### P-Channel Enhancement Mode MOSFET

#### D.Label rule

标签内容(Label content)



1	Label Size	30 * 90 mm
2	Font style	Times New Roman or Arial (或可区分英文“0”和数字“0”，“G”和“Q”的字型即可)
3	Great Power	Height: 4 mm
4	Package	Height: 2 mm
5	Date	Height: 2 mm Shipping date: YYYY/MM/DD, ex. 2008/09/12
6	Device	Height: 3 mm (Max: 16 Digit)
7	Lot	Height: 3 mm (Max: 9 Digit) Sub lot
8	D/C	Height: 3 mm (Max: 7 Digit)
9	QTY	Height: 3 mm (Max: 6 Digit) Thousand mark is no needed
10	Pb Free label	 Diameter: 1 cm bottom color: Green Font color: Black Font style: Arial
11	Halogen Free label	 Diameter: 1 cm bottom color: Green Font color: Black Font style: Arial
12	Scan info	Device / Lot / D/C / QTY , Insert “/” between every parts. for example: P3055LDG/G12345601/GGG2301/2000 DPI (Dots per inch): Over 300 dpi Code : Code 128 Height: 6 mm at least